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 \*\* CONTINUING DATA \*\*\*\*\* *NONE, TD*

 \*\* FOREIGN APPLICATIONS \*\*\*\*\* *Yes, TD*  
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## IF REQUIRED, FOREIGN FILING LICENSE GRANTED

\*\* 06/03/2004

|   |  |                              |                         |                       |                            |
|---|--|------------------------------|-------------------------|-----------------------|----------------------------|
| Foreign Priority claimed<br>35 USC 119 (a-d) conditions met | <input checked="" type="checkbox"/> yes <input type="checkbox"/> no<br><input checked="" type="checkbox"/> yes <input type="checkbox"/> no <input type="checkbox"/> Met after<br>Allowance | STATE OR<br>COUNTRY<br>JAPAN | SHEETS<br>DRAWING<br>21 | TOTAL<br>CLAIMS<br>13 | INDEPENDENT<br>CLAIMS<br>1 |
| Verified and<br>Acknowledged                                | Examiner's Signature <i>Z. Huan</i><br>Initials <i>TD</i>  |                              |                         |                       |                            |

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## TITLE

Method of manufacturing a semiconductor device to provide improved adhesion between bonding pads and ball portions of electrical connectors

FILING FEE FEES: Authority has been given in Paper

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| <input type="checkbox"/> All Fees                       |
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